

FIG. 2

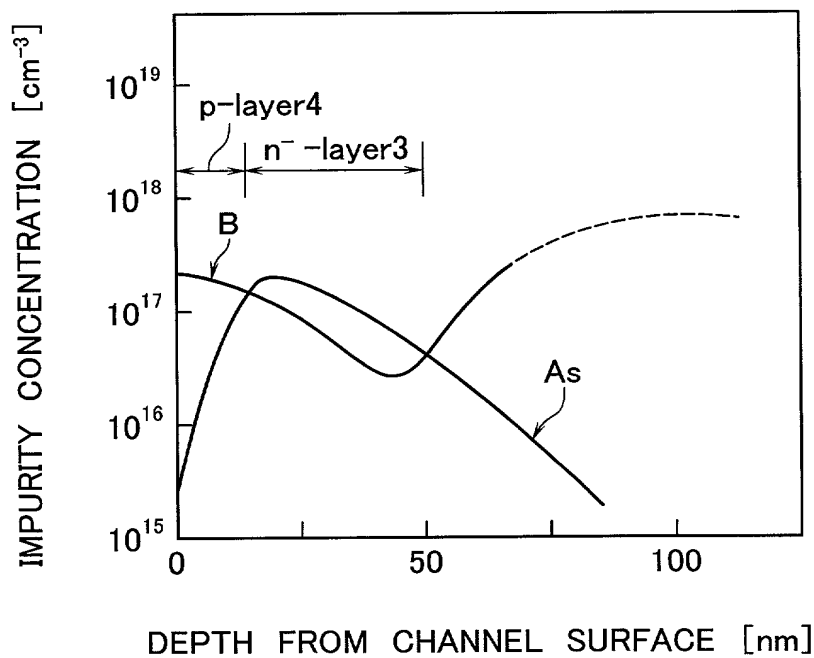


FIG. 3

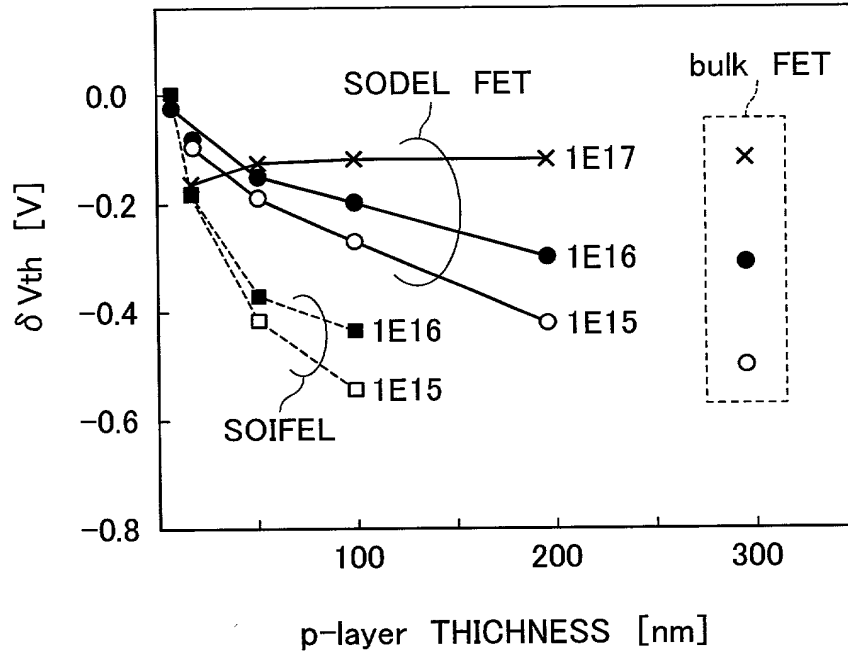


FIG. 4

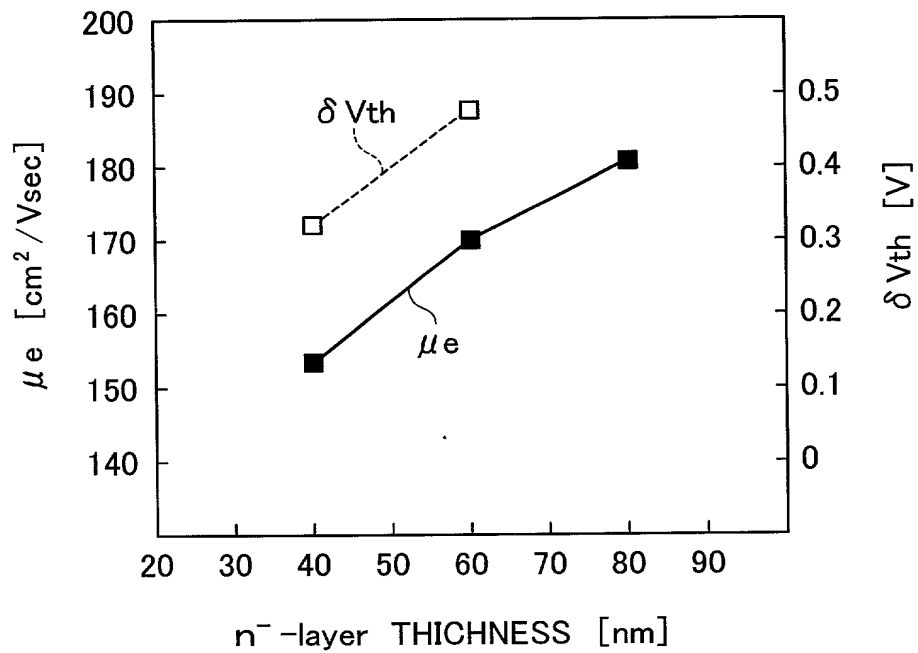


FIG. 5A

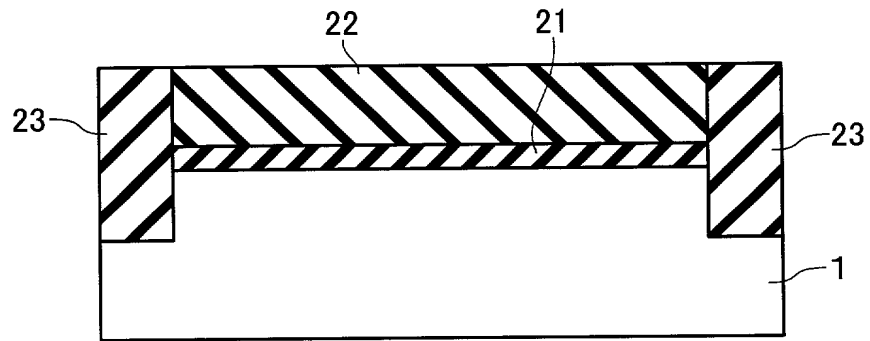


FIG. 5B

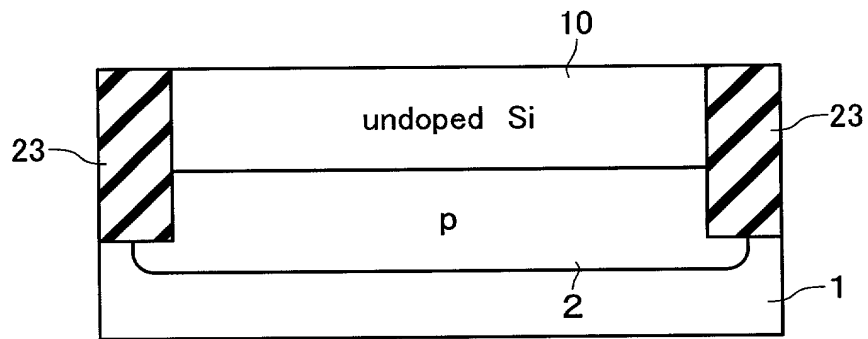


FIG. 5C

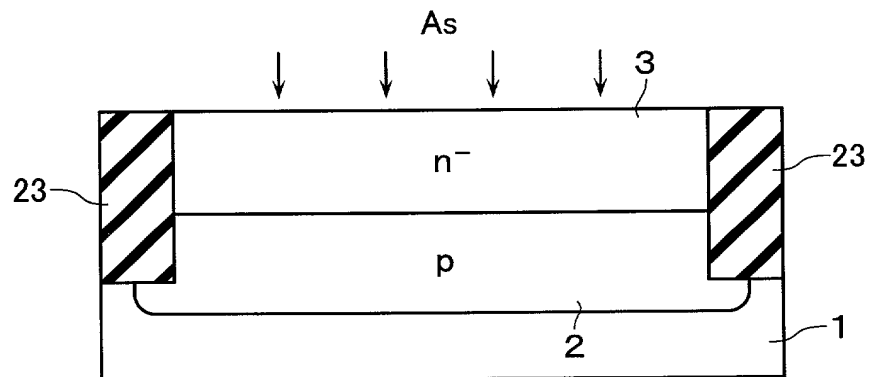


FIG. 5D

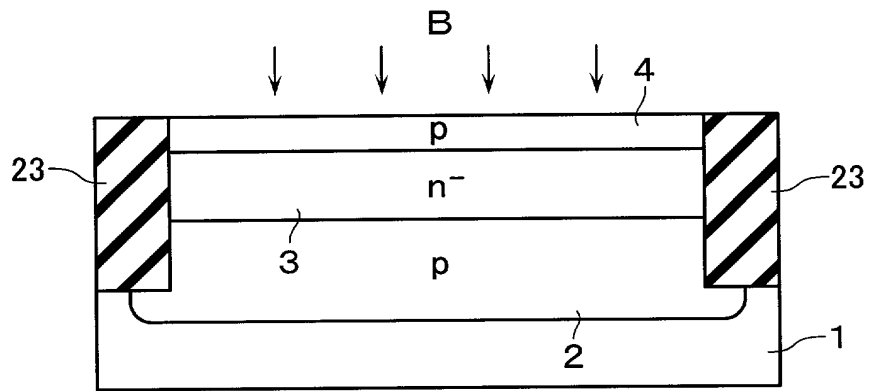


FIG. 6A

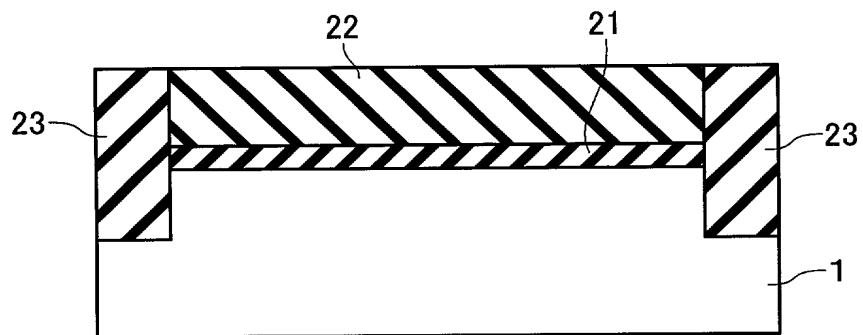


FIG. 6B

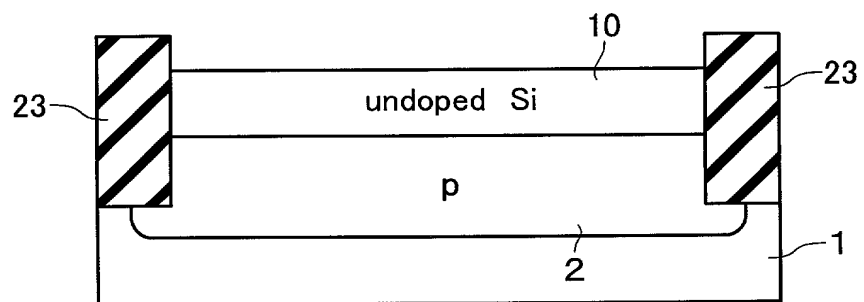


FIG. 6C

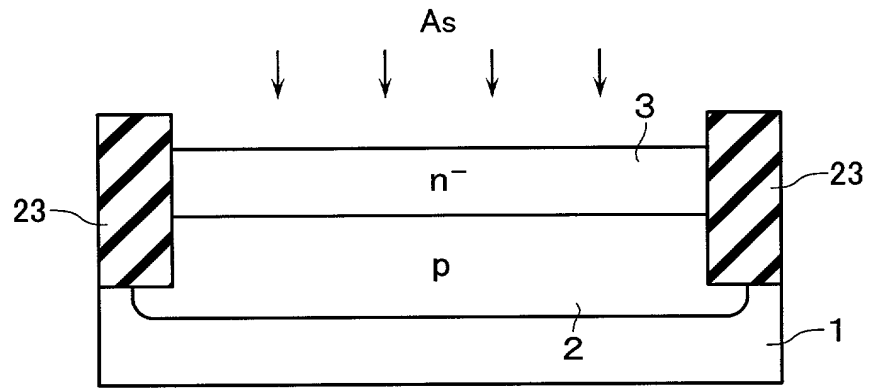


FIG. 6D

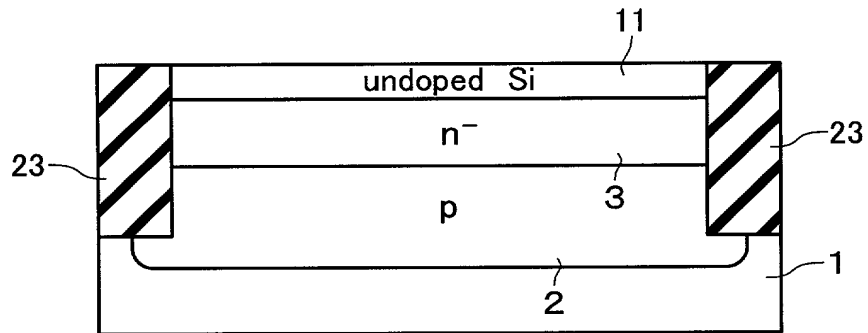


FIG. 6E

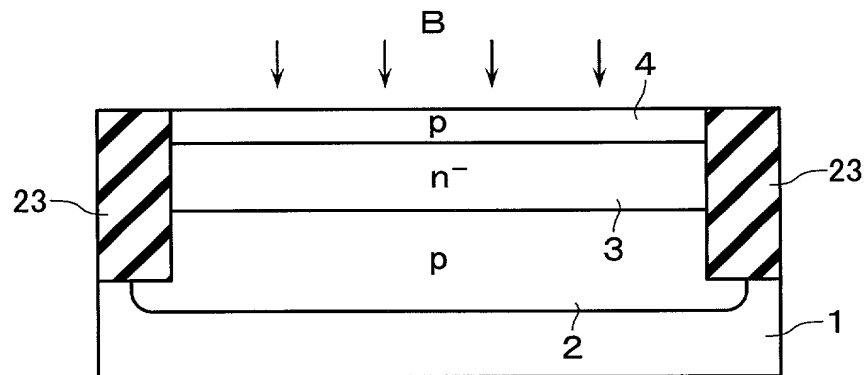


FIG. 7

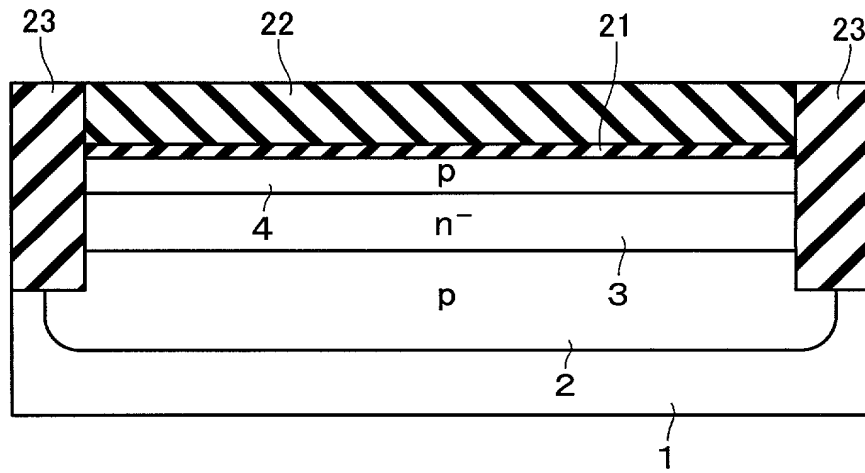


FIG. 8

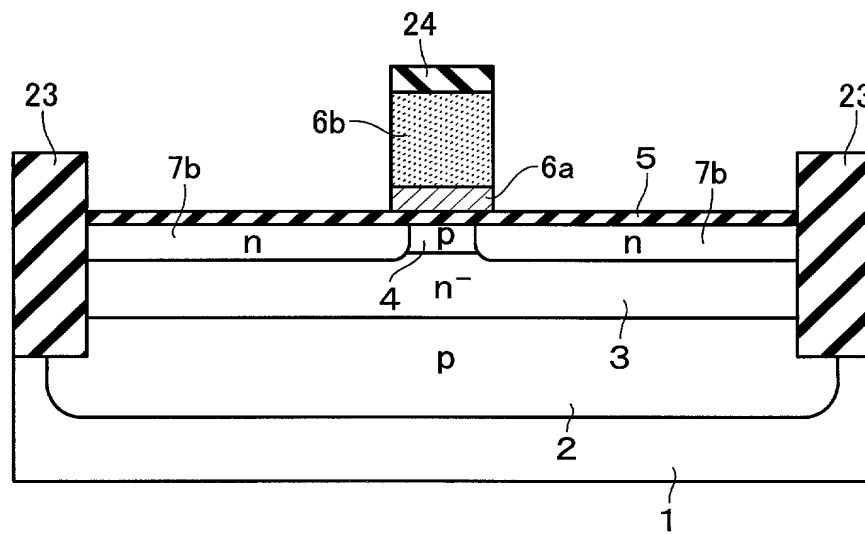


FIG. 10

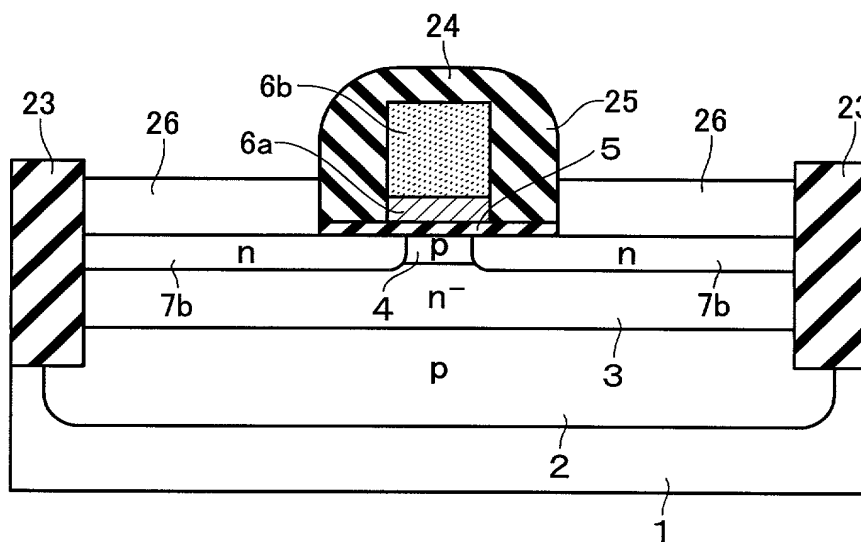


Figure 1 is a cross-sectional view of a semiconductor device 1. The device includes a substrate 3 with a p-type region 4 and n+ regions 7a. A central n- region 5 is covered by a dielectric layer 6a and a top layer 6b. A central square region 24 is embedded in the n- region. Two side regions 23 are also shown. A wire 2 connects the side regions 23.



FIG. 13

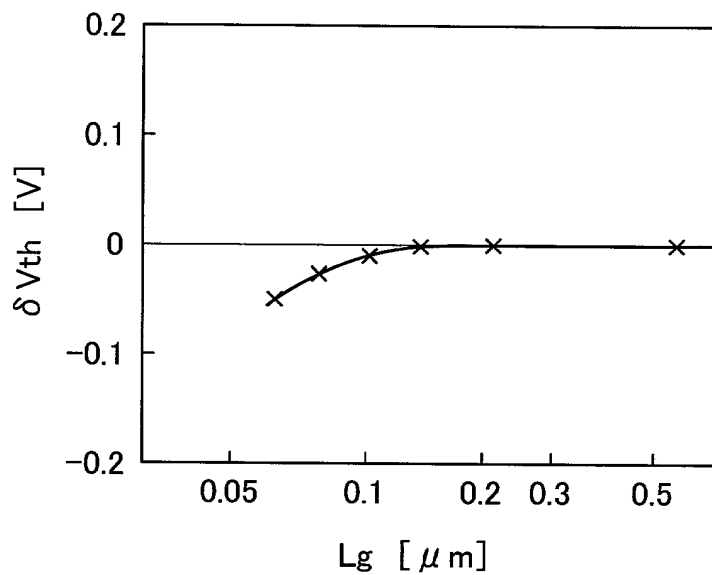


FIG. 14

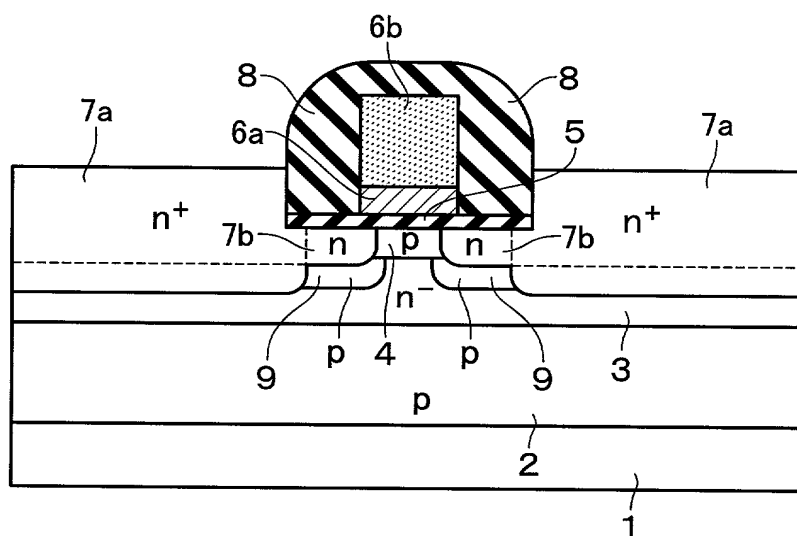


FIG. 15

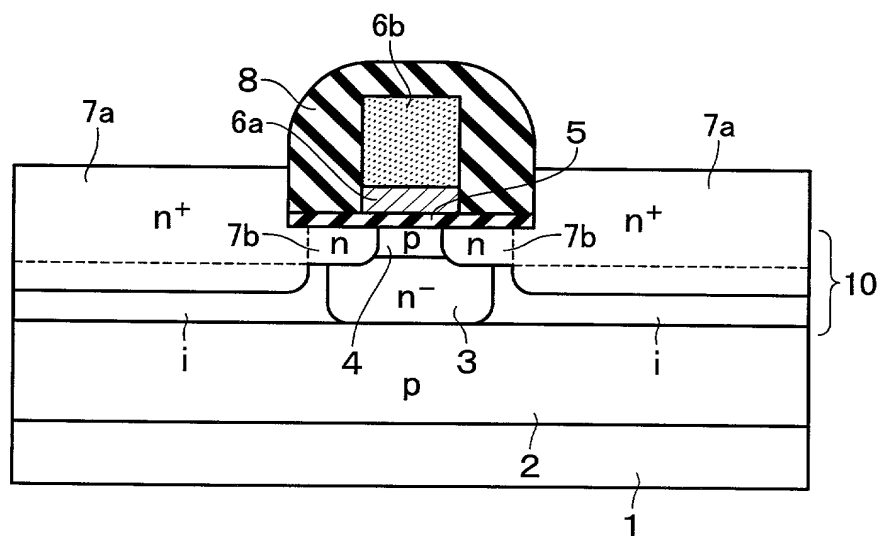


FIG. 16

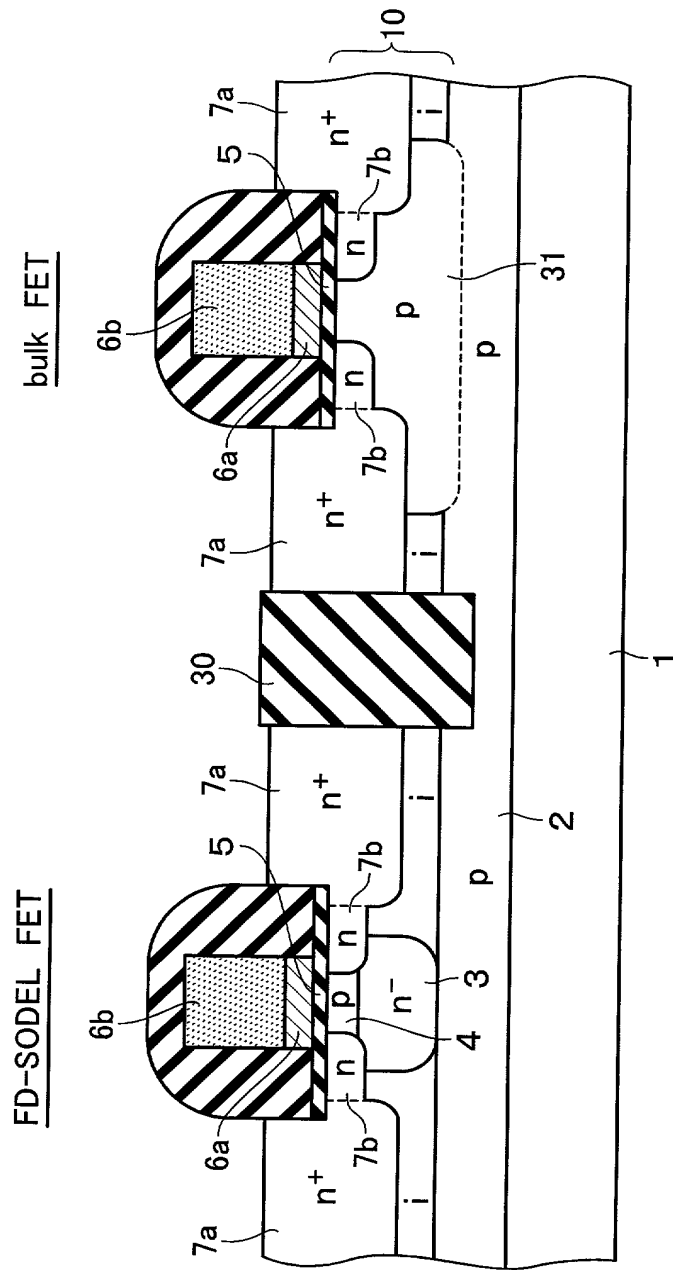


FIG. 17

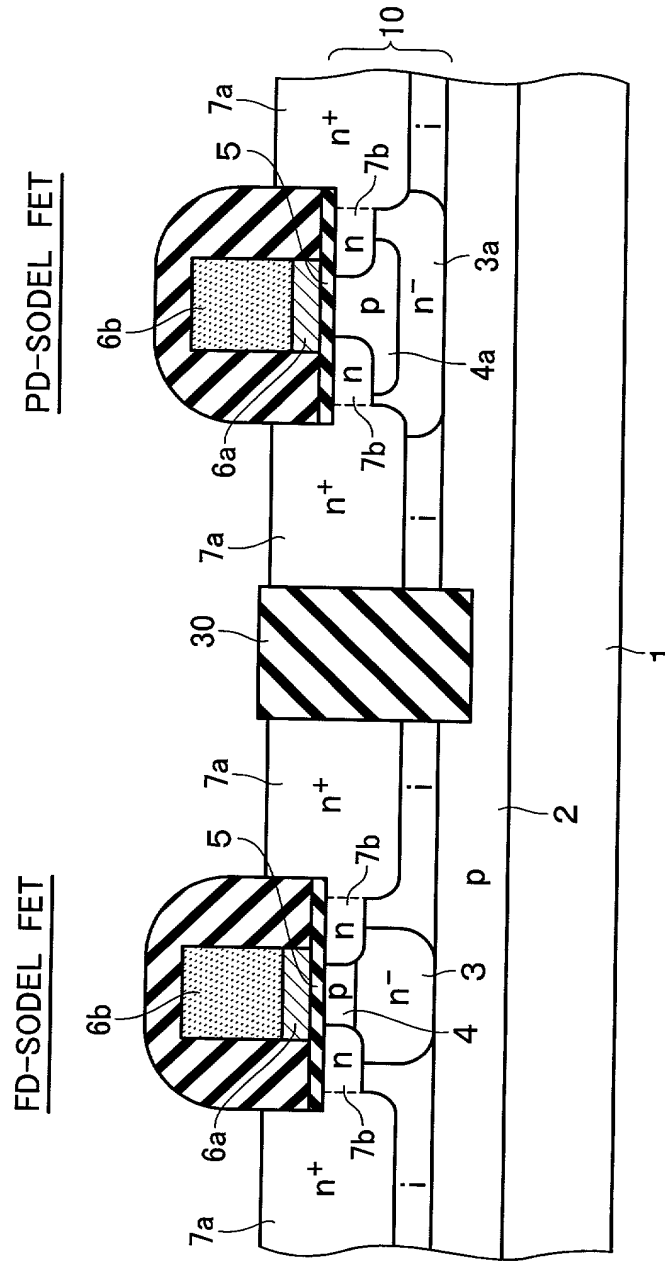


FIG. 18

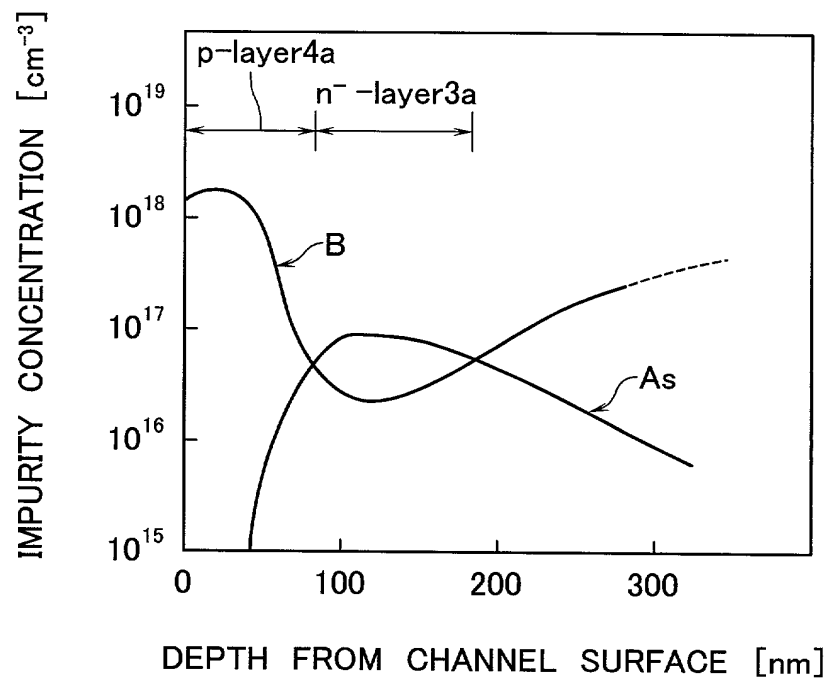


FIG. 19

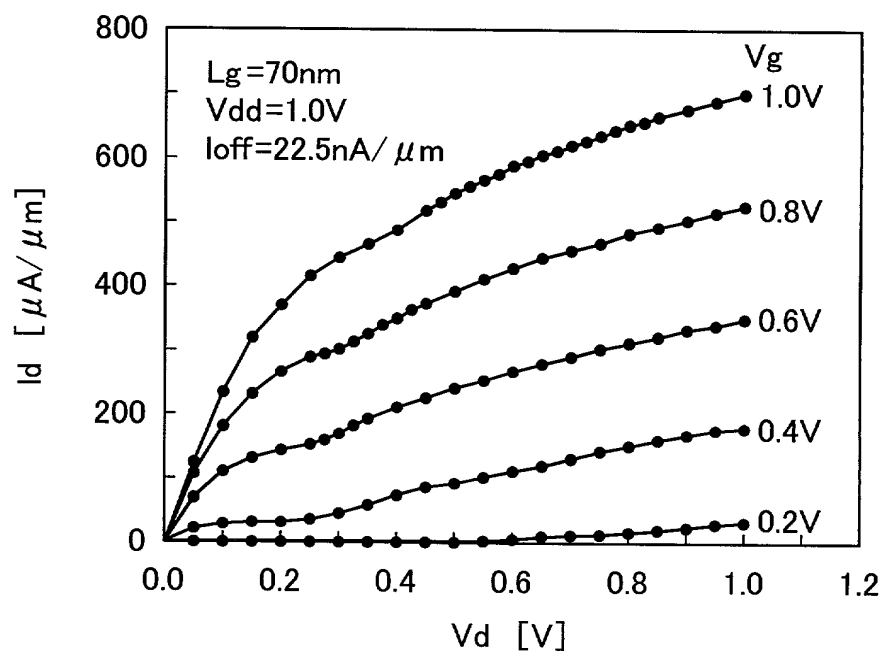


FIG. 20

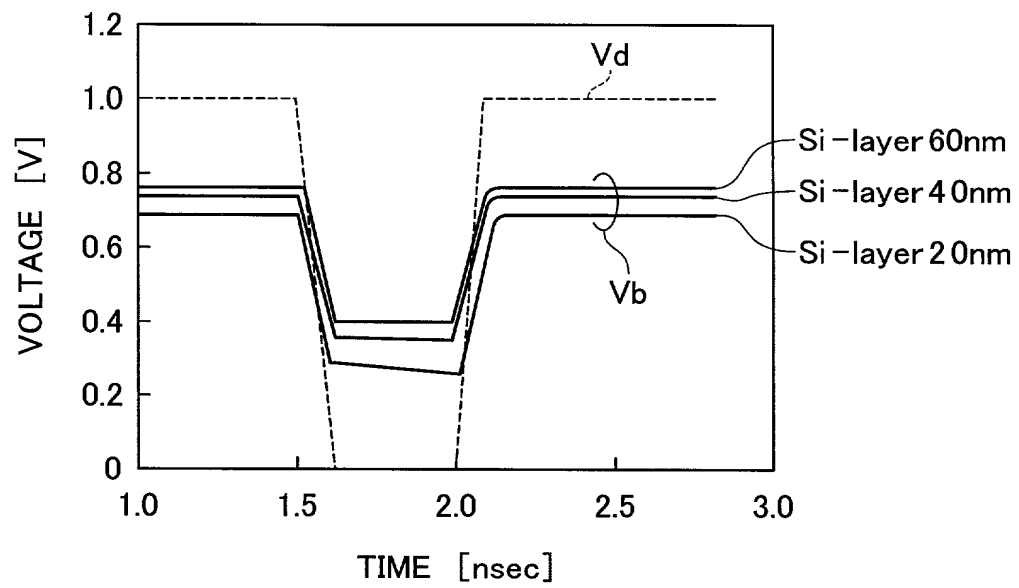


FIG. 22

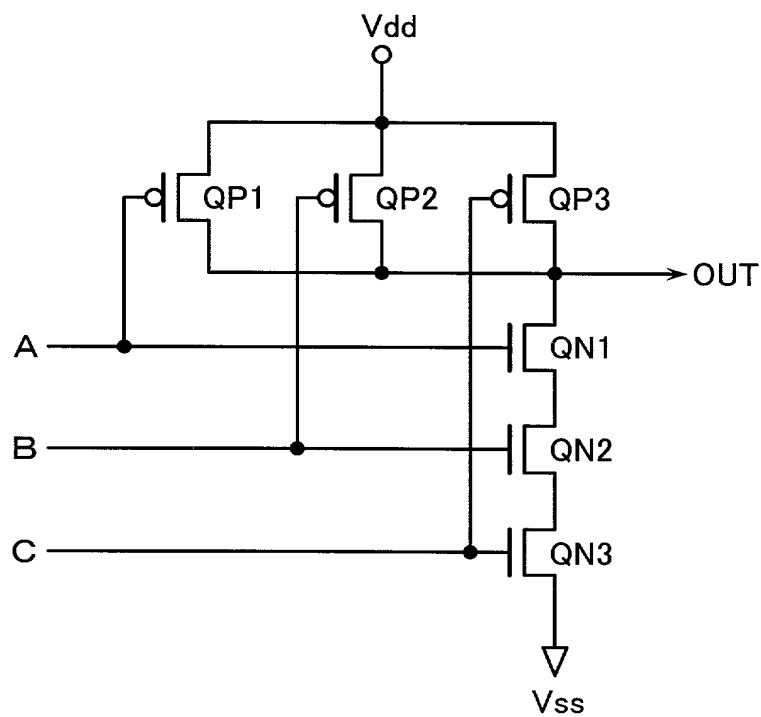


FIG. 21

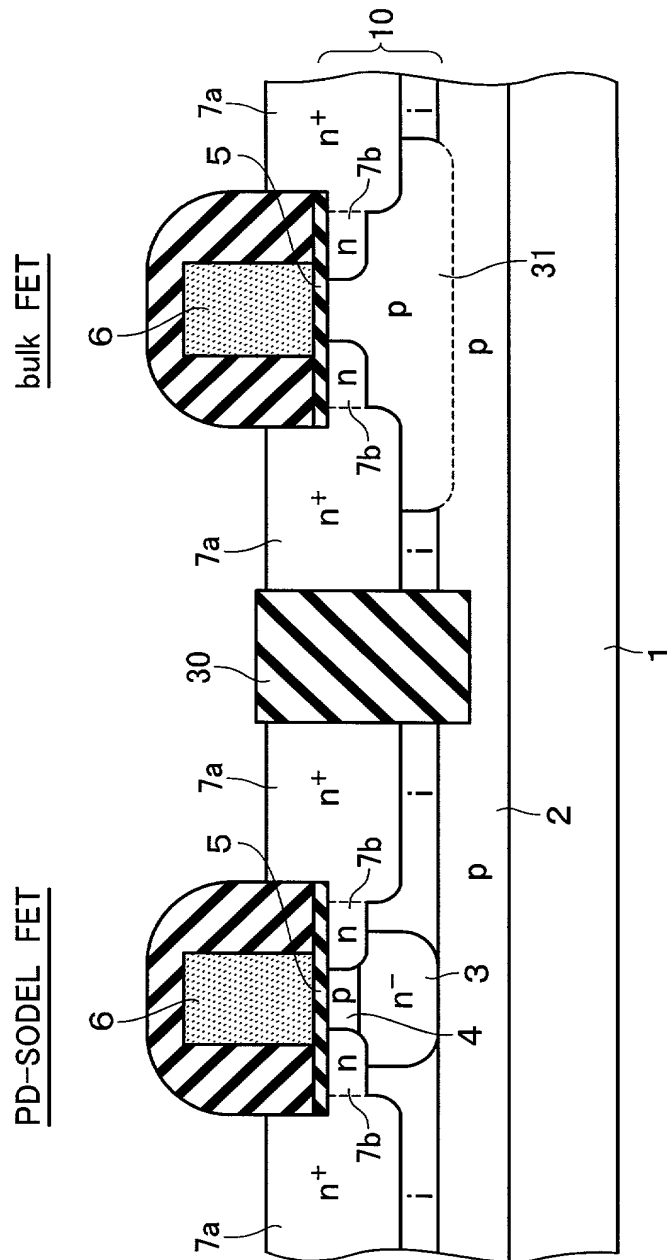


FIG. 23

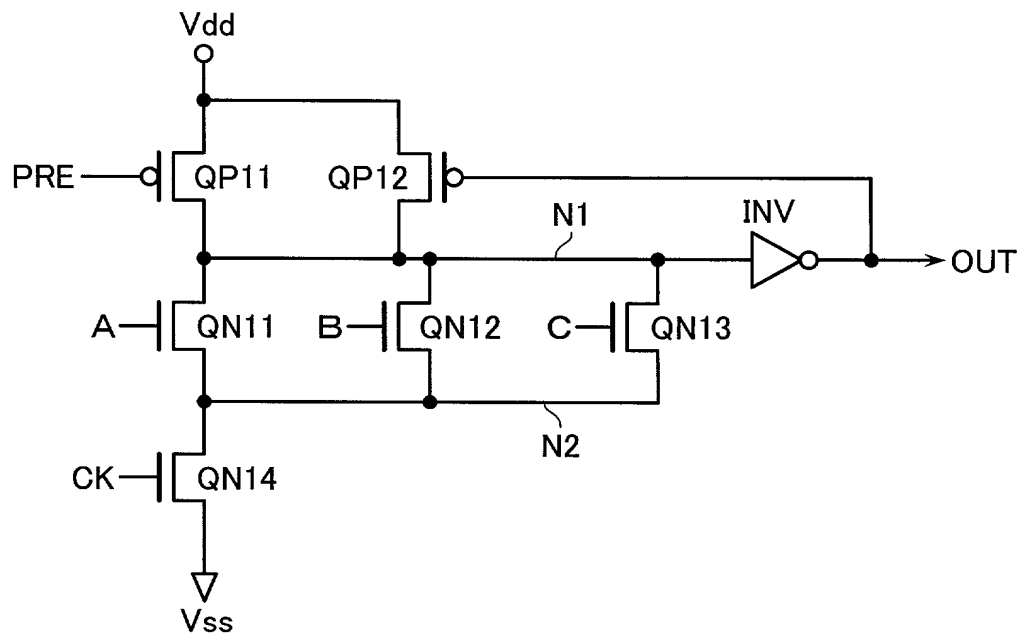


FIG. 24

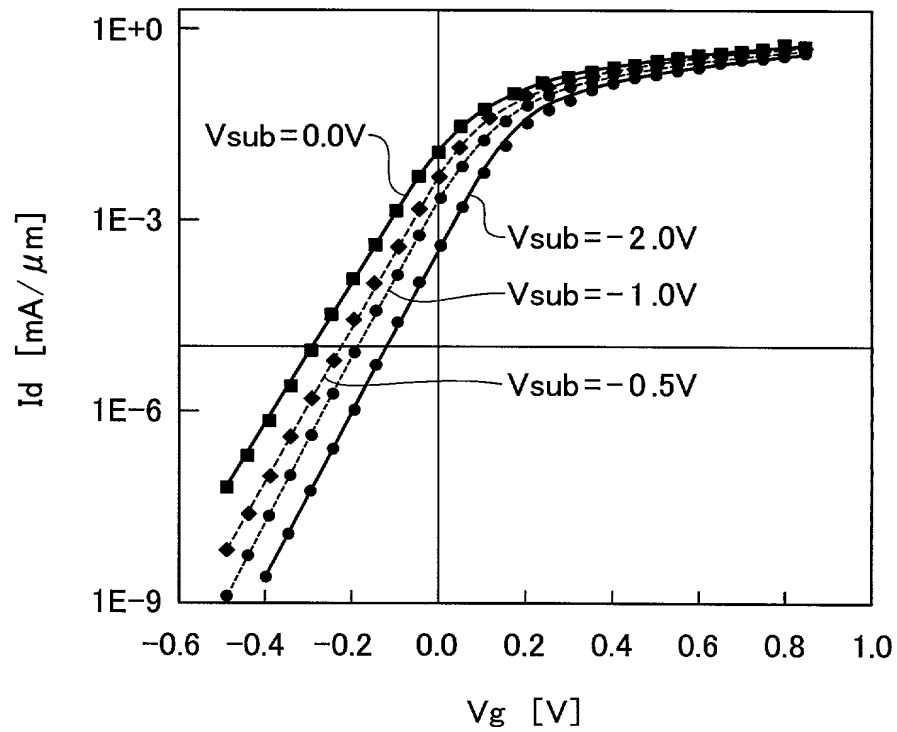


FIG. 25

